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November 2013

FQI4N90

N-Channel QFET® MOSFET

900 V, 4.2 A, 3.3 Ω

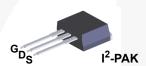
Description

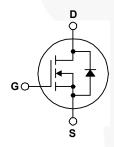
This N-Channel enhancement mode power MOSFET is • 4.2 A, 900 V, $R_{DS(on)}$ = 3.3 Ω (Max.) @ V_{GS} = 10 V, produced using Fairchild Semiconductor's proprietary planar stripe and DMOS technology. This advanced MOSFET technology has been especially tailored to reduce on-state

• Low Gate Charge (Typ. 24 nC) resistance, and to provide superior switching performance • Low Crss (Typ. 9.5 pF) and high avalanche energy strength. These devices are suitable for switched mode power supplies, active power • 100% Avalanche Tested factor correction (PFC), and electronic lamp ballasts.

Features

- $I_D = 2.1 A$





Absolute Maximum Ratings T_C = 25°C unless otherwise noted.

Symbol	Parameter		FQI4N90TU	Unit	
V _{DSS}	Drain-Source Voltage		900	V	
I _D	Drain Current - Continuous (T _C = 25°C)		4.2	Α	
	- Continuous (T _C = 100°C)		2.65	Α	
I _{DM}	Drain Current - Pulsed	Note 1)	16.8	Α	
V _{GSS}	Gate-Source Voltage		± 30	V	
E _{AS}	Single Pulsed Avalanche Energy (Note 2)		570	mJ	
I _{AR}	Avalanche Current	Note 1)	4.2	Α	
E _{AR}	Repetitive Avalanche Energy	Note 1)	14	mJ	
dv/dt	Peak Diode Recovery dv/dt (Note 3)		4.0	V	
P_{D}	Power Dissipation (T _A = 25°C) *		3.13	W	
	Power Dissipation (T _C = 25°C)		140	W	
	- Derate above 25°C		1.12	W/°C	
T _J , T _{stg}	Operating and Storage Temperature Range		-55 to +150	°C	
T _L	Maximum lead temperature for soldering, 1/8" from case for 5 seconds.		300	°C	

Thermal Characteristics

Symbol	Parameter	FQI4N90TU	Unit
R_{\thetaJC}	Thermal Resistance, Junction to Case, Max. 0.89		
В	Thermal Resistance, Junction to Ambient (Minimum Pad of 2-oz Copper), Max.	62.5	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (*1 in ² Pad of 2-oz Copper), Max.	40	

Package Marking and Ordering Information

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FQI4N90TU	FQI4N90	I ² -PAK	Tube	N/A	N/A	50 units

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
Off Cha	aracteristics					
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	900			V
ΔBV _{DSS} / ΔT _J	Breakdown Voltage Temperature Coefficient	I _D = 250 μA, Referenced to 25°C		0.9		V/°C
I _{DSS}	Zana Cata Valta na Duain Cumant	urrent $V_{DS} = 900 \text{ V}, V_{GS} = 0 \text{ V}$ $V_{DS} = 720 \text{ V}, T_{C} = 125 ^{\circ}\text{C}$			10	μΑ
	Zero Gate Voltage Drain Current				100	μΑ
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 30 V, V _{DS} = 0 V			100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	V _{GS} = -30 V, V _{DS} = 0 V			-100	nA
On Cha	aracteristics					
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$	3.0		5.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} = 10 V, I _D = 2.1 A		2.7	3.3	Ω
9 _{FS}	Forward Transconductance	V _{DS} = 50 V, I _D = 2.1 A		3.5		S
	ic Characteristics					
C _{iss}	Input Capacitance	V _{DS} = 25 V, V _{GS} = 0 V, f = 1.0 MHz		860	1100	pF
C _{oss}	Output Capacitance			90	120	pF
C _{rss}	Reverse Transfer Capacitance			9.5	12.5	pF
Switch	ing Characteristics					
t _{d(on)}	Turn-On Delay Time	V _{DD} = 450 V, I _D = 4.2 A,		25	60	ns
t _r	Turn-On Rise Time	$V_{DD} = 450 \text{ V}, I_{D} = 4.2 \text{ A},$ $R_{G} = 25 \Omega$		70	150	ns
t _{d(off)}	Turn-Off Delay Time	11.6 20 32		45	100	ns
t _f	Turn-Off Fall Time	(Note 4)		40	90	ns
Qg	Total Gate Charge	V _{DS} = 720 V, I _D = 4.2 A,		24	30	nC
Q _{gs}	Gate-Source Charge	V _{GS} = 10 V		5.8		nC
Q _{gd}	Gate-Drain Charge	(Note 4)	/	11.5		nC
Drain-S	Source Diode Characteristics a	nd Maximum Ratings				
l _S	Maximum Continuous Drain-Source Diode Forward Current				4.2	Α
I _{SM}	Maximum Pulsed Drain-Source Diode Forward Current				16.8	Α
	5 . 6 . 5 5	V _{GS} = 0 V, I _S = 4.2 A			1.4	V
V _{SD}	Drain-Source Diode Forward Voltage	VGS - 0 V, IS - 4.2 A			1.4	V
V _{SD}	Reverse Recovery Time	$V_{GS} = 0 \text{ V, } I_{S} = 4.2 \text{ A},$		440		ns

- **Notes:** 1. Repetitive rating : pulse-width limited by maximum junction temperature. 2. L = 61 mH, I $_{AS}$ = 4.2 A, V $_{DD}$ = 50 V, R $_{G}$ = 25 Ω , starting T $_{J}$ = 25°C. 3. I $_{SD}$ ≤ 4.2 A, di/dt ≤ 200 A/ μ s, V $_{DD}$ ≤ BV $_{DSS}$, starting T $_{J}$ = 25°C. 4. Essentially independent of operating temperature.

Typical Characteristics

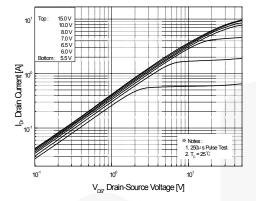


Figure 1. On-Region Characteristics

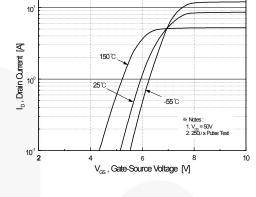


Figure 2. Transfer Characteristics

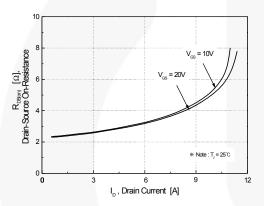


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

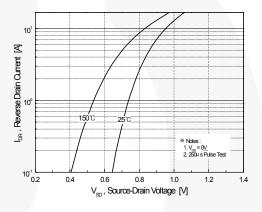


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

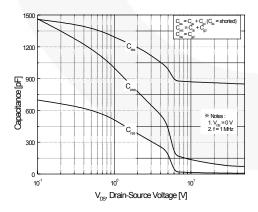


Figure 5. Capacitance Characteristics

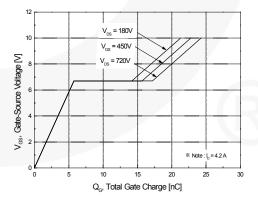


Figure 6. Gate Charge Characteristics

12 (Daily Montalized) 10 (Source Bread and Source Bread a

0.8 L -100

Typical Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

T, Junction Temperature [°C]

150

200

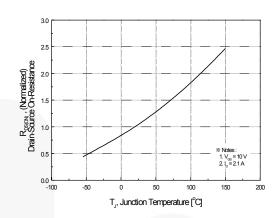


Figure 8. On-Resistance Variation vs. Temperature

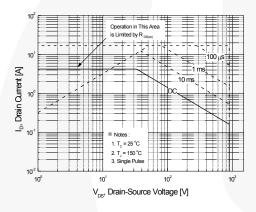


Figure 9. Maximum Safe Operating Area

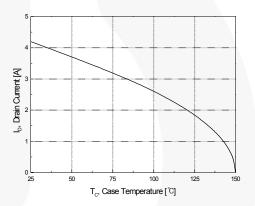


Figure 10. Maximum Drain Current vs. Case Temperature

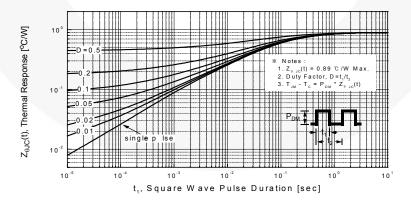


Figure 11. Transient Thermal Response Curve

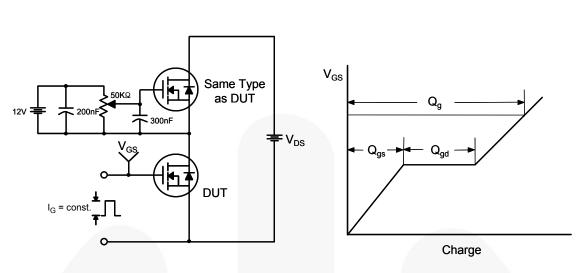


Figure 12. Gate Charge Test Circuit & Waveform

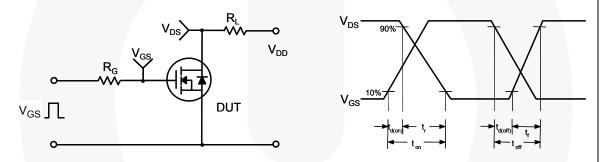


Figure 13. Resistive Switching Test Circuit & Waveforms

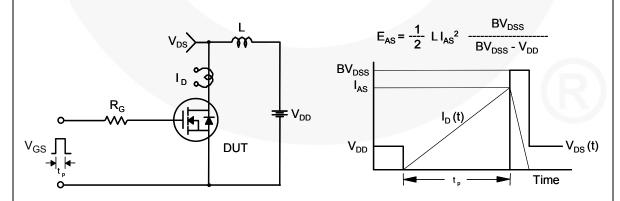
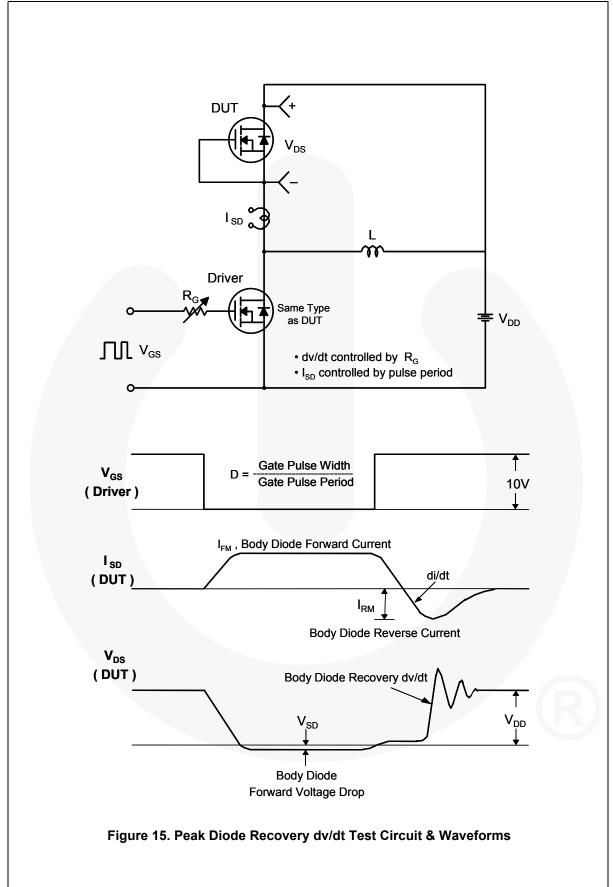


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms



Mechanical Dimensions

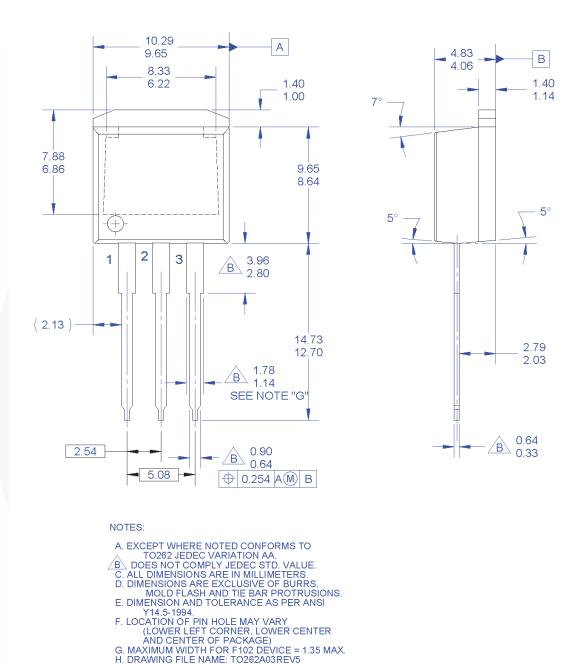


Figure 16. TO262 (I²PAK), Molded, 3-Lead, Jedec Variation AA

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